What is claimed is:

~~1. A method of manufacture of an integrated circuit packaging system comprising:~~

~~forming a package paddle;~~

~~forming a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side;~~

~~mounting an integrated circuit over the package paddle;~~

~~connecting an electrical connector to the lead and the integrated circuit; and~~

~~forming a fill layer within the hole.~~

~~2. The method as claimed in claim 1 wherein forming the lead includes forming the lead having a conductive lead top layer with the hole therethrough.~~

~~3. The method as claimed in claim 1 wherein forming the fill layer includes forming the fill layer coplanar with a conductive lead bottom layer of the lead.~~

~~4. The method as claimed in claim 1 wherein forming the package paddle includes forming the package paddle having a paddle recess with the integrated circuit mounted within the paddle recess.~~

~~5. The method as claimed in claim 1 wherein forming the lead includes forming the lead having a conductive lead bottom layer and the hole at a bottom layer periphery of the conductive lead bottom layer.~~

~~6. A method of manufacture of an integrated circuit packaging system comprising:~~

~~forming a package paddle;~~

~~forming a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side;~~

~~attaching an attach layer to the package paddle;~~

~~mounting an integrated circuit over the package paddle with the attach layer attached to the integrated circuit;~~

~~connecting an electrical connector to the lead and the integrated circuit; and~~

~~forming a fill layer within the hole.~~

~~7.~~ 2.The method as claimed in claim ~~6~~1 wherein forming the fill layer includes forming a passivation layer within the hole.

1. ~~The method as claimed in claim 6~~ A method of manufacture of an integrated circuit packaging system comprising:

forming a package paddle;

forming a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side, wherein forming the lead includes forming the lead having a lower step in the hole and an inner surface at a lower end of the hole;

attaching an attach layer to the package paddle;

mounting an integrated circuit over the package paddle with the attach layer attached to the integrated circuit;

connecting an electrical connector to the lead and the integrated circuit; and

~~8.~~ forming a fill layer exposing a bottom surface of the lead ridge and within the hole.

3. ~~The method as claimed in claim 6 wherein~~A method of manufacture of an integrated circuit packaging system comprising:

forming a package paddle;

forming a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side, wherein forming the lead includes forming the lead having a lower step in the hole and an open lower end of the hole;

attaching an attach layer to the package paddle;

mounting an integrated circuit over the package paddle with the attach layer attached to the integrated circuit;

connecting an electrical connector to the lead and the integrated circuit; and

~~9.~~ forming a fill layer exposing a bottom surface of the lead ridge and within the hole~~.~~

~~10. The method as claimed in claim 6 wherein forming the lead includes forming the lead having a top opening of the hole smaller than a bottom opening of the hole.~~

~~11. An integrated circuit packaging system comprising:~~

~~a package paddle;~~

~~a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side;~~

~~an integrated circuit over the package paddle;~~

~~an electrical connector connected to the lead and the integrated circuit; and~~

~~a fill layer within the hole.~~

~~12.~~ 6.The system as claimed in claim ~~11~~5 wherein the lead includes a conductive lead top layer with the hole therethrough.

~~13.~~ 7. The system as claimed in claim ~~11~~5 wherein the fill layer is coplanar with a conductive lead bottom layer of the lead.

~~14.~~ 8.The system as claimed in claim ~~11~~5 wherein the package paddle includes a paddle recess with the integrated circuit mounted within the paddle recess.

~~15.~~ 9.The system as claimed in claim ~~11~~5 wherein the lead includes a conductive lead bottom layer and the hole at a bottom layer periphery of the conductive lead bottom layer.

~~16. The system as claimed in claim 11 further comprising:~~

~~an attach layer attached to the package paddle; and~~

~~wherein:~~

~~the integrated circuit over the package paddle with the attach layer attached to the integrated circuit.~~

~~17.~~ 10.The system as claimed in claim ~~16~~5 wherein the fill layer is a passivation layer within the hole.

5. ~~The system as claimed in claim 16~~ An integrated circuit packaging system comprising:

a package paddle;

a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side, wherein the lead includes a lower step in the hole and an inner surface at a lower end of the hole;

an attach layer attached to the package paddle;

an integrated circuit over the package paddle, wherein the integrated circuit is over the package paddle with the attach layer attached to the integrated circuit;

an electrical connector connected to the lead and the integrated circuit;

~~18.~~ a fill layer exposing a bottom surface of the lead ridge and within the hole.

~~19~~.11 ~~The system as claimed in claim 16~~ An integrated circuit packaging system comprising:

a package paddle;

a lead adjacent the package paddle, the lead having a hole in a lead body top side and a lead ridge protruding from a lead non-horizontal side, wherein the lead includes a lower step in the hole and an open lower end of the hole~~.~~

an attach layer attached to the package paddle;

an integrated circuit over the package paddle, wherein the integrated circuit is over the package paddle with the attach layer attached to the integrated circuit;

an electrical connector connected to the lead and the integrated circuit;

~~19.~~ a fill layer exposing a bottom surface of the lead ridge and within the hole.

~~20.The system as claimed in claim 16 wherein the lead includes a top opening of the hole smaller than a bottom opening of the hole.~~

4 The method as claimed in claim 3 wherein forming the fill layer includes forming a passivation layer within the hole.

12. The system as claimed in claim 11 wherein the fill layer is a passivation layer within the hole.

13. The system as claimed in claim 11 wherein the lead includes a conductive lead top layer with the hole therethrough.

14. The system as claimed in claim 11 wherein the fill layer is coplanar with a conductive lead bottom layer of the lead.

15. The system as claimed in claim 11 wherein the package paddle includes a paddle recess with the integrated circuit mounted within the paddle recess.

~~20.~~ 16.The system as claimed in claim 11 wherein the lead includes a conductive lead bottom layer and the hole at a bottom layer periphery of the conductive lead bottom layer.